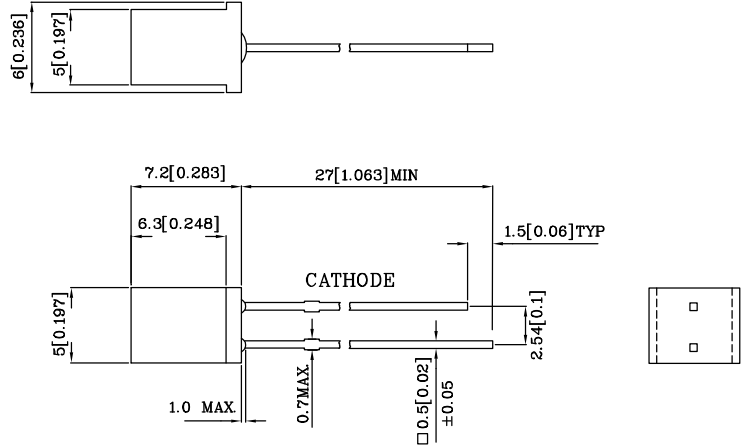


Features

- LOW POWER CONSUMPTION.
- ULTRA BRIGHTNESS IS AVAILABLE.
- WIDE VIEWING ANGLE.
- RELIABLE AND RUGGED.
- EXCELLENT UNIFORMITY OF LIGHT OUTPUT.
- IDEAL AS FLUSH MOUNTED PANEL INDICATORS.
- LONG LIFE - SOLID STATE RELIABILITY.
- RoHS COMPLIANT.



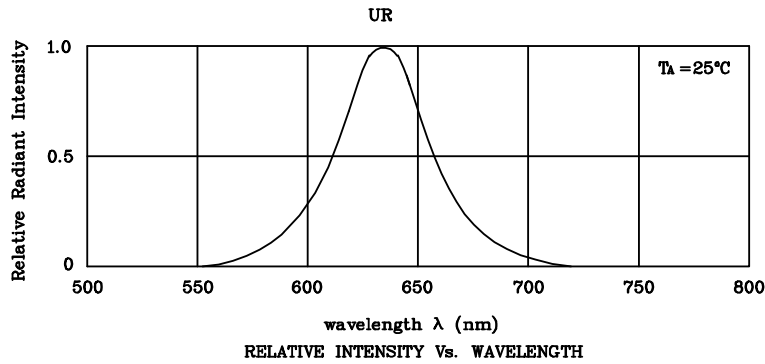
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

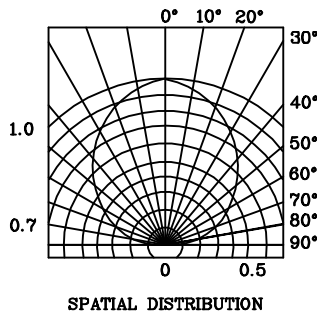
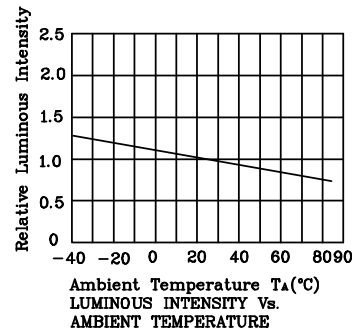
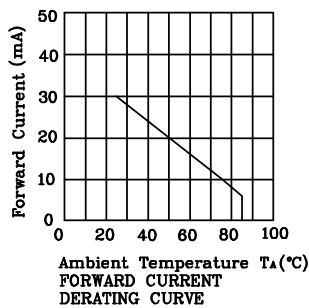
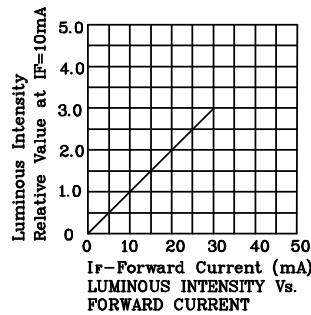
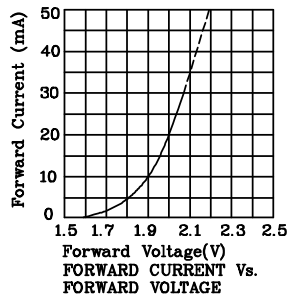
Absolute maximum ratings (TA=25°C)		UR (GaAsP/ GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	160	mA
Power Dissipation	P _T	105	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UR (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	1.9	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (I _F =10mA)	λ _P	627	nm
Wavelength of Dominant Emission (I _F =10mA)	λ _D	625	nm
Spectral Line Full Width At Half-Maximum (I _F =10mA)	Δλ	45	nm
Capacitance (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =10mA) mcd		Wavelength nm λ _P	Viewing Angle 2 θ 1/2
				min.	typ.		
XSUR23D	Red	GaAsP/GaP	Red Diffused	3	5	627	110°
Published Date : MAY 26,2005 Drawing No : XDSA2519 V3 Checked : B.L.LIU P.1/3							



❖ UR



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XSUR23D

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.